Xuejun Fan

List of Publications by Year
in descending order

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216
papers

3,664
citations

218677
26
h-index

206112
48
g-index

218
all docs

218
docs citations

218
times ranked

2353
citing authors

#	ARTICLE	IF	CITATIONS
1	A review of small heat pipes for electronics. Applied Thermal Engineering, 2016, 96, 1-17.	6.0	224
2	Heat Transfer of Aviation Kerosene at Supercritical Conditions. Journal of Thermophysics and Heat Transfer, 2009, 23, 543-550.	1.6	177
3	Experimental investigations and model study of moisture behaviors in polymeric materials. Microelectronics Reliability, 2009, 49, 861-871.	1.7	143
4	Recent advances in 2D/nanostructured metal sulfide-based gas sensors: mechanisms, applications, and perspectives. Journal of Materials Chemistry A, 2020, 8, 24943-24976.	10.3	115
5	Ultra-High Sensitive NO₂ Gas Sensor Based on Tunable Polarity Transport in CVD-WS₂/IGZO p-N Heterojunction. ACS Applied Materials & Interfaces, 2019, 11, 40850-40859.	8.0	105
6	Investigation of Vaporized Kerosene Injection and Combustion in a Supersonic Model Combustor. Journal of Propulsion and Power, 2006, 22, 103-110.	2.2	102
7	Interfacial Delamination Mechanisms During Soldering Reflow With Moisture Preconditioning. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 252-259.	1.3	90
8	PoF-Simulation-Assisted Reliability Prediction for Electrolytic Capacitor in LED Drivers. IEEE Transactions on Industrial Electronics, 2016, 63, 6726-6735.	7.9	86
9	Degradation modeling of mid-power white-light LEDs by using Wiener process. Optics Express, 2015, 23, A966.	3.4	70
10	High Selective Gas Detection for small molecules based on Germanium selenide monolayer. Applied Surface Science, 2018, 433, 575-581.	6.1	68
11	Dual stage modeling of moisture absorption and desorption in epoxy mold compounds. Microelectronics Reliability, 2012, 52, 1401-1408.	1.7	66
12	An acceleration model for lead-free (SAC) solder joint reliability under thermal cycling. , 2008, , .		62
13	Combustion and Ignition of Thermally Cracked Kerosene in Supersonic Model Combustors. Journal of Propulsion and Power, 2007, 23, 317-324.	2.2	60
14	Tailoring the Mechanical Properties of Highâ€Aspectâ€Ratio Carbon Nanotube Arrays using Amorphous Silicon Carbide Coatings. Advanced Functional Materials, 2014, 24, 5737-5744.	14.9	53
15	Degradation Mechanisms of Mid-Power White-Light LEDs Under High-Temperatureâ€"Humidity Conditions. IEEE Transactions on Device and Materials Reliability, 2015, 15, 220-228.	2.0	52
16	Lumen degradation modeling of white-light LEDs in step stress accelerated degradation test. Reliability Engineering and System Safety, 2016, 154, 152-159.	8.9	48
17	Rapid Degradation of Mid-Power White-Light LEDs in Saturated Moisture Conditions. IEEE Transactions on Device and Materials Reliability, 2015, 15, 478-485.	2.0	47
18	Experimental Verification and Optimization Analysis of Warpage for Panel-Level Fan-Out Package. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1721-1728.	2.5	47

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19	Driving Mechanisms of Delamination Related Reliability Problems in Exposed Pad Packages. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 260-268.	1.3	45
20	Wafer level packaging (WLP): Fan-in, fan-out and three-dimensional integration. , 2010, , .		45
21	Color Shift Investigations for LED Secondary Optical Designs: Comparison between BPA-PC and PMMA. Optical Materials, 2015, 45, 37-41.	3.6	45
22	Design and Reliability in Wafer Level Packaging. , 2008, , .		43
23	Machine Learning and Digital Twin Driven Diagnostics and Prognostics of Lightâ€Emitting Diodes. Laser and Photonics Reviews, 2020, 14, 2000254.	8.7	43
24	Thermal Cracking and Heat Sink Capacity of Aviation Kerosene Under Supercritical Conditions. Journal of Thermophysics and Heat Transfer, 2011, 25, 450-456.	1.6	42
25	A novel lifetime prediction for integrated LED lamps by electronic-thermal simulation. Reliability Engineering and System Safety, 2017, 163, 14-21.	8.9	35
26	Effects of Voids on Mechanical and Thermal Properties of the Die Attach Solder Layer Used in High-Power LED Chip-Scale Packages. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1254-1262.	2.5	35
27	Product level accelerated lifetime test for indoor LED luminaires. , 2013, , .		32
28	Degradation of Microcellular PET reflective materials used in LED-based products. Optical Materials, 2015, 49, 79-84.	3.6	31
29	In-situ Characterization of Moisture Absorption and Desorption in a Thin BT Core Substrate. , 2007, , .		30
30	Effect of Sintering Pressure on the Porosity and the Shear Strength of the Pressure-Assisted Silver Sintering Bonding. IEEE Transactions on Device and Materials Reliability, 2018, 18, 240-246.	2.0	29
31	Prediction of Lumen Depreciation and Color Shift for Phosphor-Converted White Light-Emitting Diodes Based on A Spectral Power Distribution Analysis Method. IEEE Access, 2017, 5, 24054-24061.	4.2	28
32	Design and adjustment of the graphene work function via size, modification, defects, and doping: a first-principle theory study. Nanoscale Research Letters, 2017, 12, 642.	5.7	28
33	Influence of Material Combinations on Delamination Failures in a Cavity-Down TBGA Package. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 651-658.	1.3	25
34	Modeling techniques for board level drop test for a wafer-level package. , 2008, , .		25
35	Buckling of Functionally Graded Cylindrical Shells under Combined Loads. Mechanics of Advanced Materials and Structures, 2011, 18, 337-346.	2.6	25
36	Effects of Nanostructure and Coating on the Mechanics of Carbon Nanotube Arrays. Advanced Functional Materials, 2016, 26, 1233-1242.	14.9	25

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37	High-performance humidity sensor using Schottky-contacted SnS nanoflakes for noncontact healthcare monitoring. Nanotechnology, 2020, 31, 055501.	2.6	25
38	Micromechanical Modeling of Stress Evolution Induced During Cure in a Particle-Filled Electronic Packaging Polymer. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 676-683.	1.3	24
39	Effect of Finite Element Modeling Techniques on Solder Joint Fatigue Life Prediction of Flip-Chip BGA Packages. , 0, , .		24
40	Colour shift and mechanism investigation on the PMMA diffuser used in LED-based luminaires. Optical Materials, 2016, 54, 282-287.	3.6	24
41	Indentation hardness, plasticity and initial creep properties of nanosilver sintered joint. Results in Physics, 2019, 12, 712-717.	4.1	24
42	Lifetime Prediction of Ultraviolet Light-Emitting Diodes Using a Long Short-Term Memory Recurrent Neural Network. IEEE Electron Device Letters, 2020, 41, 1817-1820.	3.9	24
43	A dual stage model of anomalous moisture diffusion and desorption in epoxy mold compounds. , 2011, , .		23
44	JEDEC board drop test simulation for wafer level packages (WLPs). , 2009, , .		22
45	Color Shift Failure Prediction for Phosphor-Converted White LEDs by Modeling Features of Spectral Power Distribution with a Nonlinear Filter Approach. Materials, 2017, 10, 819.	2.9	22
46	Development and application of ANN model for property prediction of supercritical kerosene. Computers and Fluids, 2020, 209, 104665.	2.5	22
47	Mechanics of moisture for polymers: Fundamental concepts and model study. , 2008, , .		21
48	Board level temperature cycling study of large array Wafer Level Package. , 2009, , .		21
49	Finite element modeling on electromigration of solder joints in wafer level packages. Microelectronics Reliability, 2010, 50, 547-555.	1.7	21
50	A hybrid prediction method on luminous flux maintenance of high-power LED lamps. Applied Thermal Engineering, 2016, 95, 482-490.	6.0	21
51	Thermal/luminescence characterization and degradation mechanism analysis on phosphor-converted white LED chip scale packages. Microelectronics Reliability, 2017, 74, 179-185.	1.7	21
52	Optimal Design of Life Testing for High-Brightness White LEDs Using the Six Sigma DMAIC Approach. IEEE Transactions on Device and Materials Reliability, 2015, 15, 576-587.	2.0	20
53	In-situ characterization of moisture absorption and hygroscopic swelling of silicone/phosphor composite film and epoxy mold compound in LED packaging. Microelectronics Reliability, 2018, 84, 208-214.	1.7	20
54	General coupling model for electromigration and one-dimensional numerical solutions. Journal of Applied Physics, 2019, 125, .	2.5	20

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55	Thermal kinetic and mechanical behaviors of pressure-assisted Cu nanoparticles sintering: A molecular dynamics study. Results in Physics, 2020, 19, 103486.	4.1	19
56	A convectionâ€“diffusion porous media model for moisture transport in polymer composites: Model development and validation. Journal of Polymer Science, Part B: Polymer Physics, 2015, 53, 1440-1449.	2.1	18
57	Modeling nonlinear moisture diffusion in inhomogeneous media. Microelectronics Reliability, 2017, 75, 162-170.	1.7	18
58	High Moisture Accelerated Mechanical Behavior Degradation of Phosphor/Silicone Composites Used in White Light-Emitting Diodes. Polymers, 2019, 11, 1277.	4.5	17
59	Reliability Assessment of Light-Emitting Diode Packages With Both Luminous Flux Response Surface Model and Spectral Power Distribution Method. IEEE Access, 2019, 7, 68495-68502.	4.2	17
60	Microchannel Thermal Management System With Two-Phase Flow for Power Electronics Over 500 W/cm² Heat Dissipation. IEEE Transactions on Power Electronics, 2020, 35, 10592-10600.	7.9	17
61	Deep machine learning of the spectral power distribution of the LED system with multiple degradation mechanisms. Journal of Mechanics, 2020, 37, 172-183.	1.4	17
62	Emerging MOSFET packaging technologies and their thermal evaluation. , 0, , .		16
63	EFFECTS OF ENTRY CONDITIONS ON CRACKED KEROSENE-FUELED SUPERSONIC COMBUSTOR PERFORMANCE. Combustion Science and Technology, 2007, 179, 2199-2217.	2.3	16
64	Finite-Element Analysis and Experimental Test for a Capped-Die Flip-Chip Package Design. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1308-1316.	2.5	16
65	A Reliability Prediction for Integrated LED Lamp With Electrolytic Capacitor-Free Driver. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1081-1088.	2.5	16
66	Development, validation, and application of thermal modeling for a MCM power package. , 0, , .		15
67	A First-Principle Theoretical Study of Mechanical and Electronic Properties in Graphene Single-Walled Carbon Nanotube Junctions. Materials, 2017, 10, 1300.	2.9	15
68	Reliability Analysis of SnPb and SnAgCu Solder Joints in FC-BGA Packages with Thermal Enabling Preload. , 0, , .		14
69	Phosphorâ€“silicone interaction effects in high power white light emitting diode packages. Journal of Materials Science: Materials in Electronics, 2017, 28, 17557-17569.	2.2	14
70	A stochastic process based reliability prediction method for LED driver. Reliability Engineering and System Safety, 2018, 178, 140-146.	8.9	14
71	Hydrolysis kinetic study of CaAlSiN3:Eu2+ red phosphor with both water immersion test and first-principles calculation. Journal of Luminescence, 2020, 219, 116874.	3.1	14
72	Machine-Learning Assisted Prediction of Spectral Power Distribution for Full-Spectrum White Light-Emitting Diode. IEEE Photonics Journal, 2020, 12, 1-18.	2.0	14

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73	System level reliability assessment for high power light-emitting diode lamp based on a Bayesian network method. Measurement: Journal of the International Measurement Confederation, 2021, 176, 109191.	5.0	14
74	Effects of design, structure and material on thermal-mechanical reliability of large array wafer level packages. , 2009, , .		13
75	Moisture diffusion and integrated stress analysis in encapsulated microelectronics devices. , 2011, , .		13
76	A degradation model of aluminum electrolytic capacitors for LED drivers. , 2015, , .		13
77	Effects of Sintering Pressure on the Densification and Mechanical Properties of Nanosilver Double-Side Sintered Power Module. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 963-972.	2.5	13
78	Stress/strain characterization in electronic packaging by micro-Raman spectroscopy: A review. Microelectronics Reliability, 2021, 118, 114045.	1.7	13
79	Room temperature ppt-level NO₂ gas sensor based on SnO _x /SnS nanostructures with rich oxygen vacancies. 2D Materials, 2021, 8, 045006.	4.4	13
80	Sensitivity Investigation of Substrate Thickness and Reflow Profile on Wafer Level Film Failures in 3D Chip Scale Packages by Finite Element Modeling. , 2007, , .		12
81	Slow Cycle Fatigue Creep Performance of Pb-Free (LF) Solders. , 2007, , .		12
82	Package structural integrity analysis considering moisture. , 2008, , .		12
83	Effects of Package Level Structure and Material Properties on Solder Joint Reliability Under Impact Loading. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 52-60.	2.5	12
84	Modeling of moisture over-saturation and vapor pressure in die-attach film for stacked-die chip scale packages. Journal of Materials Science: Materials in Electronics, 2016, 27, 481-488.	2.2	12
85	Photometric and Colorimetric Assessment of LED Chip Scale Packages by Using a Step-Stress Accelerated Degradation Test (SSADT) Method. Materials, 2017, 10, 1181.	2.9	12
86	Molecular dynamic study for concentration-dependent volume relaxation of vacancy. Microelectronics Reliability, 2021, 120, 114127.	1.7	12
87	Experimental Investigation on the Sintering Kinetics of Nanosilver Particles Used in High-Power Electronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1101-1109.	2.5	12
88	Optical degradation mechanisms of mid-power white-light LEDs in LM-80-08 tests. Microelectronics Reliability, 2015, 55, 2654-2662.	1.7	11
89	Thermal, optical and electrical analysis on phosphor-converted white LED Chip Scale Packages with both experiment and simulation. , 2016, , .		11
90	A new hermetic sealing method for ceramic package using nanosilver sintering technology. Microelectronics Reliability, 2018, 81, 143-149.	1.7	11

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91	Design of a Fan-Out Panel-Level SiC MOSFET Power Module Using Ant Colony Optimization-Back Propagation Neural Network. IEEE Transactions on Electron Devices, 2021, 68, 3460-3467.	3.0	11
92	Solder Joint Reliability Risk Estimation by AI-Assisted Simulation Framework with Genetic Algorithm to Optimize the Initial Parameters for AI Models. Materials, 2021, 14, 4835.	2.9	11
93	High-temperature nanoindentation characterization of sintered nano-copper particles used in high power electronics packaging. Results in Physics, 2022, 33, 105168.	4.1	11
94	Root Cause Mechanism for Delamination/Cracking in Stacked Die Chip Scale Packages. Semiconductor Manufacturing, Proceedings of the IEEE International Symposium on, 2006, , .	0.0	10
95	Wafer-Level Film Selection for Stacked-Die Chip Scale Packages. , 2007, , .		10
96	Shock performance study of solder joints in wafer level packages. , 2009, , .		10
97	Effects of Vapor Pressure and Super-Hydrophobic Nanocomposite Coating on Microelectronics Reliability. Engineering, 2015, 1, 384-390.	6.7	10
98	Degradation Mechanism Decoupling of Mid-Power White-Light LEDs by SPD Simulation. IEEE Transactions on Electron Devices, 2016, 63, 2807-2814.	3.0	10
99	A Review on Water Vapor Pressure Model for Moisture Permeable Materials Subjected to Rapid Heating. Applied Mechanics Reviews, 2018, 70, .	10.1	10
100	Polarized Raman spectroscopyâ€“stress relationship considering shear stress effect. Optics Letters, 2019, 44, 4682.	3.3	10
101	Advances in Wafer Level Packaging (WLP). Microelectronics Reliability, 2010, 50, 479-480.	1.7	9
102	Assessment of current density singularity in electromigration of solder bumps. , 2011, , .		9
103	Dynamic stability of flexible electronic structures under step loads. European Journal of Mechanics, A/Solids, 2016, 58, 247-255.	3.7	9
104	The Effects of Graphene Stacking on the Performance of Methane Sensor: A First-Principles Study on the Adsorption, Band Gap and Doping of Graphene. Sensors, 2018, 18, 422.	3.8	9
105	Stress analysis of pressure-assisted sintering for the double-side assembly of power module. Soldering and Surface Mount Technology, 2019, 31, 20-27.	1.5	9
106	The interface adhesion of CaAlSiN3: Eu2+ phosphor/silicone used in light-emitting diode packaging: A first principles study. Applied Surface Science, 2020, 510, 145251.	6.1	9
107	Sintering mechanism of Ag nanoparticle-nanoflake: a molecular dynamics simulation. Journal of Materials Research and Technology, 2022, 16, 640-655.	5.8	9
108	Investigation of thermal performance of various power-device packages. , 2008, , .		8

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109	The effect of atomic density gradient in electromigration. International Journal of Materials and Structural Integrity, 2012, 6, 36.	0.1	8
110	A novel hybrid method for reliability prediction of high-power LED luminaires. , 2013, , .		8
111	Liquid-phase exfoliated SnS as a semiconductor coating filler to enhance corrosion protection performance. Physical Chemistry Chemical Physics, 2019, 21, 18179-18187.	2.8	8
112	Dynamic prediction of optical and chromatic performances for a light-emitting diode array based on a thermal-electrical-spectral model. Optics Express, 2020, 28, 13921.	3.4	8
113	Tensile characterization and constitutive modeling of sintered nano-silver particles over a range of strain rates and temperatures. Microelectronics Reliability, 2022, 132, 114536.	1.7	8
114	Thermal shock fracture in a surface-cracked plate. Engineering Fracture Mechanics, 1992, 41, 223-228.	4.3	7
115	Field Condition Reliability Assessment for SnPb and SnAgCu Solder Joints in Power Cycling Including Mini Cycles. , 0, , .		7
116	Reliability challenges and design considerations for Wafer-Level packages. , 2008, , .		7
117	Color shift acceleration on mid-power LED packages. Microelectronics Reliability, 2017, 78, 294-298.	1.7	7
118	Degradation mechanism analysis for phosphor/silicone composites aged under high temperature and high humidity condition. , 2017, , .		7
119	Investigation of dimensional and heat source effects in Lock-In Thermography applications in semiconductor packages. Applied Thermal Engineering, 2017, 113, 673-683.	6.0	7
120	Effects of humidity and phosphor on silicone/phosphor composite in white light-emitting diode package. Journal of Materials Science: Materials in Electronics, 2019, 30, 20471-20478.	2.2	7
121	Reliability enhancement of wafer level packages with nano-column-like hollow solder ball structures. , 2011, , .		6
122	Finite Element Modeling of System Design and Testing Conditions for Component Solder Ball Reliability Under Impact. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1802-1810.	2.5	6
123	Effect of temperature gradient on moisture diffusion in high power devices and the applications in LED packages. , 2013, , .		6
124	Achieving warpage-free packaging: A capped-die flip chip package design. , 2015, , .		6
125	Lumen decay prediction in LED lamps. , 2016, , .		6
126	Analysis of photoluminescence mechanisms and thermal quenching effects for multicolor phosphor films used in high color rendering white LEDs. , 2016, , .		6

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127	Thermal Inductance in GaN Devices. IEEE Electron Device Letters, 2016, 37, 1473-1476.	3.9	6
128	Studies of the light output properties for a GaN based blue LED using an electro-optical simulation method. Microelectronics Reliability, 2017, 74, 173-178.	1.7	6
129	Application of water activity-based theory for moisture diffusion in electronic packages using ANSYS. , 2018, , .		6
130	Improved Finite Element Modeling of Moisture Diffusion Considering Discontinuity at Material Interfaces in Electronic Packages. , 2019, , .		6
131	Die and Package Level Thermal and Thermal/Moisture Stresses in 3D Packaging: Modeling and Characterization. Springer Series in Advanced Microelectronics, 2017, , 293-332.	0.3	6
132	Accelerated Moisture Sensitivity Test Methodology for Stacked-Die Molded Matrix Array Package. , 2007, , .		5
133	Stress Analysis of Hygrothermal Delamination of Quad Flat No-Lead (QFN) Packages. , 2008, , .		5
134	Larger Array Fine Pitch Wafer Level Package Drop Test Reliability. , 2009, , .		5
135	Investigation of photoluminescence and thermal effect of phosphor films used in phosphor-converted white LEDs. , 2015, , .		5
136	Junction temperature measurement to optimize thermal design of LED arrays. , 2015, , .		5
137	LED's luminous flux lifetime prediction using a hybrid numerical approach. , 2015, , .		5
138	In-situ characterization of moisture absorption and hygroscopic swelling of silicone/phosphor composite film and epoxy mold compound in LED packaging. , 2017, , .		5
139	Electromigration simulation of flip chip CSP LED. , 2017, , .		5
140	A Novel Interconnected Structure of Graphene-Carbon Nanotubes for the Application of Methane Adsorption. IEEE Sensors Journal, 2018, 18, 1555-1561.	4.7	5
141	A design and qualification of LED flip Chip-on-Board module with tunable color temperatures. Microelectronics Reliability, 2018, 84, 140-148.	1.7	5
142	Implementation of General Coupling Model of Electromigration in ANSYS. , 2020, , .		5
143	Insights into the high-sulphur aging of sintered silver nanoparticles: An experimental and ReaxFF study. Corrosion Science, 2021, 192, 109846.	6.6	5
144	A new method for equivalent acceleration of JEDEC moisture sensitivity levels. , 2008, , .		4

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145	Finite element modeling of anomalous moisture diffusion with dual stage model. , 2012, , .		4
146	In-situ moisture desorption characterization of epoxy mold compound. , 2012, , .		4
147	Accelerated lifetime test for isolated components in linear drivers of high-voltage LED system. , 2013, , .		4
148	Does current crowding induce vacancy concentration singularity in electromigration?. , 2014, , .		4
149	Luminous flux modeling for high power LED automotive headlamp module. , 2017, , .		4
150	A Unified and Versatile Model Study for Moisture Diffusion. , 2017, , .		4
151	Engineering Design and Manufacturing Education through Research Experience for High School Teachers. Procedia Manufacturing, 2018, 26, 1340-1348.	1.9	4
152	A Reliability Prediction Methodology for LED Arrays. IEEE Access, 2019, 7, 8127-8134.	4.2	4
153	Tunable electronic and optical properties of the WS₂/IGZO heterostructure<i>via</i>an external electric field and strain: a theoretical study. Physical Chemistry Chemical Physics, 2019, 21, 14713-14721.	2.8	4
154	Effect of porous Cu addition on the microstructure and mechanical properties of SnBi-xAg solder joints. Applied Physics A: Materials Science and Processing, 2020, 126, 1.	2.3	4
155	Evaluating the moisture resistance of Y3Al5O12: Ce3+ phosphor used in high power white LED packaging. Microelectronics Reliability, 2021, 121, 114130.	1.7	4
156	Effects of temperature and grain size on diffusivity of aluminium: electromigration experiment and molecular dynamic simulation. Journal of Physics Condensed Matter, 2022, 34, 175401.	1.8	4
157	Genetic Algorithmâ€“Assisted Design of Redistribution Layer Vias for a Fan-Out Panel-Level SiC MOSFET Power Module Packaging. , 2022, , .		4
158	Toughening analysis for warm prestressing. International Journal of Pressure Vessels and Piping, 1991, 48, 1-8.	2.6	3
159	Simulation of diffusion controlled intermetallic formation of Au/Al interface. , 2012, , .		3
160	Wafer level system packaging and integration for solid state lighting (SSL). , 2012, , .		3
161	Thermal behavior of flip chip LED packages using electrical conductive adhesive and soldering methods. , 2013, , .		3
162	Thermal analysis and optimization of IGBT power electronic module based on layout model. , 2016, , .		3

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163	Overdriving reliability of chip scale packaged LEDs: Quantitatively analyzing the impact of component. Microelectronics Reliability, 2017, 78, 197-204.	1.7	3
164	A SPICE-based Transient Thermal-Electronic Model for LEDs. , 2019, , .		3
165	Lifetime Prediction of Ultraviolet Light-emitting Diodes with Accelerated Wiener Degradation Process. , 2019, , .		3
166	A Direct Multi-Field Coupling Methodology for Modeling Moisture-Induced Stresses and Delamination in Electronic Packages. , 2020, , .		3
167	Prognostics of radiation power degradation lifetime for ultraviolet light-emitting diodes using stochastic data-driven models. Energy and AI, 2021, 4, 100066.	10.6	3
168	Sulfur-Rich Ageing Mechanism of Silicone Encapsulant Used in LED Packaging: An Experimental and Molecular Dynamic Simulation Study. Frontiers in Materials, 2022, 9, .	2.4	3
169	Practical aspects of thermomechanical modeling in electronics packaging: A case study with a SiC power package. Microelectronics Reliability, 2022, 132, 114514.	1.7	3
170	Implementation of Fully Coupled Electromigration Theory in COMSOL. , 2022, , .		3
171	Investigations of solder ball drop reliability: BGA versus WLP. , 2011, , .		2
172	A POF based breakdown method for LED lighting color shift reliability. , 2015, , .		2
173	Vapor pressure prediction for stacked-chip packages in reflow by convection-diffusion model. , 2015, , .		2
174	Electrical-thermo-mechanical Simulation for aluminum wire bonds in SiC Schottky diode packages. , 2016, , .		2
175	A systematic approach for reliability assessment of electrolytic capacitor-free LED drivers. , 2016, , .		2
176	Electro-optical simulation of a GaN based blue LED chip. , 2016, , .		2
177	Buckling of a stiff thin film on a compliant substrate under anisotropic biaxial prestrain. Science China: Physics, Mechanics and Astronomy, 2016, 59, 1.	5.1	2
178	Optimization of reflow soldering process for white LED chip-scale-packages on substrate. , 2017, , .		2
179	Investigation of affecting parameters on the effective modulus and natural frequency of wavy carbon nanotubes. Journal of Physics and Chemistry of Solids, 2018, 121, 121-127.	4.0	2
180	Prediction of kerosene properties at supercritical pressures by Artificial Neural Network. , 2018, , .		2

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181	On the Uniqueness and Sensitivity of Nanoindentation Testing for Determining Elastic and Plastic Material Properties of Electroplating Copper Filled in Through-Silicon-Via (TSV). , 2018, , .		2
182	Constitutive Modeling of Sintered Nano-silver Particles: A Variable-order Fractional Model versus an Anand Model. , 2021, , .		2
183	Determination of stress components in a complex stress condition using micro-Raman spectroscopy. Optics Express, 2021, 29, 30319.	3.4	2
184	Flow Modulation and Mixing Enhancement of Highly Underexpanded Jet by Vortex Excitation. AIAA Journal, 2020, 58, 2462-2474.	2.6	2
185	Thermal Stresses in Wafer-Level Packaging. , 2014, , 5432-5442.		2
186	Reliability optimization of gold-tin eutectic die attach layer in HEMT package. , 2016, , .		2
187	Fatigue failure modeling of wire bonds of high power LED packages with a multiphysics simulation method. , 2016, , .		2
188	Improved Lawnmower Blade Design and Optimization. , 2009, , .		1
189	Cause analysis on highly depreciated indoor LED product in CSA020. , 2013, , .		1
190	Thermal analysis and optimization design of LED streetlight module. , 2013, , .		1
191	A lifetime prediction method for Solid State Lighting power converters based on SPICE models and finite element thermal simulations. , 2014, , .		1
192	Correlation of activation energy between LEDs and luminaires in the lumen depreciation test. , 2014, , .		1
193	Investigation of Geometry, Frequency and Material's Effects in Lock-In Thermography Applications in Semiconductor Packages. , 2016, , .		1
194	Luminescence mechanism analysis on high power tunable color temperature Chip-on-Board white LED modules. , 2017, , .		1
195	A PoF and statistics combined reliability prediction for LED arrays in lamps. , 2017, , .		1
196	Study of ultraviolet assisted cure mechanism of the phosphor/silicone composites used in White LEDs. , 2018, , .		1
197	A probabilistic physics-of-failure reliability assessment approach for integrated LED lamps. , 2018, , .		1
198	How Much Baking Time is Needed for Moisture-Sensitive Packages?. , 2019, , .		1

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199	Investigation of thermal performance of various power-device packages. , 2008, , .		0
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